

PCN#20240411006.1
Qualification of FFAB using qualified Process Technology, Die Revision, and additional BOM options for select devices
Change Notification / Sample Request

Date: April 11, 2024
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) [process](#).

TI requires acknowledgement of receipt of this notification within 30 days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 30 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 30 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

This particular PCN is related to TI's multiyear transition plan for our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). DFAB will remain open, but will focus on 200-mm production, with a smaller set of technologies. SFAB will close no earlier than 2024 and no later than 2025. As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

Change Management Team
SC Business Services

20240411006.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
OPA695IDR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20240411006.1	PCN Date:	April 11, 2024		
Title:	Qualification of FFAB using qualified Process Technology, Die Revision, and additional BOM options for select devices				
Customer Contact:	Change Management team	Dept:	Quality Services		
Proposed 1st Ship Date:	July 10, 2024	Sample requests accepted until:	May 11, 2024*		
*Sample requests received after May 11, 2024 will not be supported.					
Change Type:					
<input type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Design		
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet		
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change		
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site		
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process		
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material		
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process		
<input checked="" type="checkbox"/>		<input checked="" type="checkbox"/>	Wafer Fab Site		
<input checked="" type="checkbox"/>		<input checked="" type="checkbox"/>	Wafer Fab Materials		
<input checked="" type="checkbox"/>		<input checked="" type="checkbox"/>	Wafer Fab Process		
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the addition of FFAB using the BICOMHD qualified process technology and additional BOM options for the device listed below.					
Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
SFAB	CBC10	150 mm	FFAB	BICOMHD	200 mm
The die was also changed as a result of the process change.					
Construction differences are as follows:					
	Current	Additional			
Bond wire composition, diameter	Au, 1.15 mils	Cu, 1.0 mil			
Mold Compound	4209640	4211880			
Mount Compound	4205846	4147858			
Qual details are provided in the Qual Data Section.					
Reason for Change:					
These changes are part of our multiyear plan to transition products from our 150-millimeter and 200-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Impact on Environmental Ratings:					
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.					
RoHS	REACH	Green Status	IEC 62474		
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change		
Changes to product identification resulting from this PCN:					
Fab Site Information:					
Chip Site	Chip Site Origin	Chip Site Country	Chip Site City		

	Code (20L)	Code (21L)	
SH-BIP-1	SHE	USA	Sherman
FR-BIP-1	TID	DEU	Freising

Die Rev:

Current

New

Die Rev [2P]	Die Rev [2P]
C	A

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 2Q:
 MSL 2 /260C/1 YEAR SEAL DT
 MSL 1 /235C/UNLIM 03/29/04
 OPT:
 ITEM: 39
 LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0053317
 (20L) CSO: SHE (21L) CCO:USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

OPA695IDR

For alternate parts with similar or improved performance, please visit the product page on [TI.com](https://www.ti.com)

TI Information
Selective Disclosure

Qualification Report
Approve Date 18-NOVEMBER -2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: OPA695IDR	QBS Reference: OPA2810IDGKR	QBS Reference: LM393DR	QBS Reference: LM393DR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	3/231/0	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/3000/0	-	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	3/15/0	3/15/0
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-	-
ESD	E2	ESD CDM	-	250 Volts	-	3/9/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	3/9/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	3/9/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/90/0	-	-

- QBS: Qual By Similarity
- Qual Device OPA695IDR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-NPD-2110-030

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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